Title (en)

FILLER FOR JOINT AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

ZUSATZWERKSTOFF FÜR FÜGEVERBINDUNGEN UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

MATERIAU D'APPORT POUR ASSEMBLAGES ET SON PROCEDE DE PRODUCTION

Publication

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Application

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Abstract (en)

[origin: WO2005115680A1] The invention relates to a filler for thermal production of a joint or a material layer which is metallically connected to the base material of /or on objects made of light metal and/or zinc alloys with a conductivity of more than 110 W/mK, in addition to a method for the production thereof with means for the preparation thereof in situ and/or storage. According to the invention, the filler is provided in the form of an unwindable filler wire, comprising a covering which is optionally provided with a surface coating made of polymer (s) and graphite, consisting of aluminium and/or magnesium and/or zinc or a deformable alloy of said metals with a thermal conductivity of more than 110 W/mK and a core made of compacted powder. The core material consists of metal powder and/or powder of at least one metal compound and/or non-metal compound and/or agent giving off gas at a high temperature and/or at least one component forming slag. Production is characterized by manufacture of a filling wire known per se, however an optionally coated covering made of a ductile light metal or similar alloy is provided, wherein the coils are wound in a suitable manner and are provided with a protection against moisture.

IPC 8 full level

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